

# ABSTRACT OF THE DISCLOSURE

The present invention prevents electrostatic discharge damage which may occur when a device chip which has a circuit with fuses mounted thereon is packaged by COG packaging, 5 without increasing an area occupied on the device chip. The height from the chip substrate surface to the top face 138b of the chip terminal 103b formed on the chip substrate surface 136 is formed to be higher than the height from the chip substrate surface to the top face 138a of the fuse terminal 103a. By 10 this, an electrostatic discharge occurs at the chip terminal side when packaged in a COG packaging, so an electrostatic discharge does not occur to the fuse terminal side.